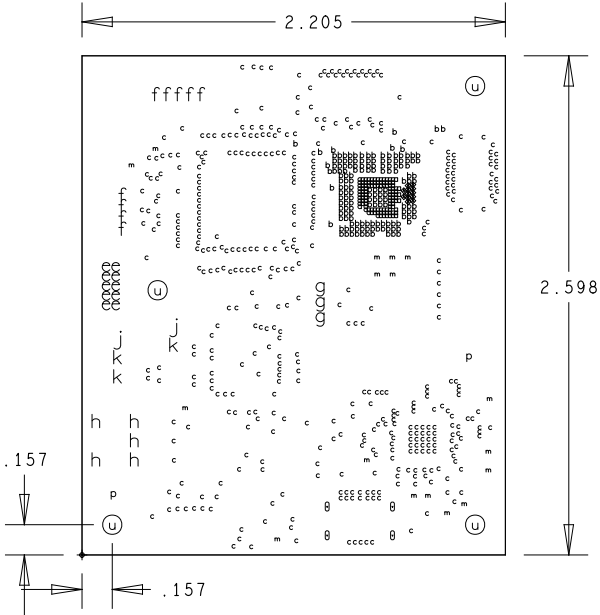


	0.0005	STACKUP	SOLDERMASK
LAYER 1	0.0020		1/2oz Sig (Std Plt) - 50 Ohms - 0.005 width 68 Ohms - 0.004 width 100 Ohms Differential - 0.0041 width/0.00575 Space
	0.0027		FR408H
LAYER 2	0.0006		1/2oz P/G
	0.0040		FR408H
LAYER 3	0.0006		1/2oz SIG - 50 Ohms - 0.005 width 100 Ohms Differential - 0.00425 width/0.00575 Space
	0.0072		FR408H
LAYER 4	0.0012		1oz P/G
	X.XXXX		FR408H
LAYER 5	0.0012		1oz P/G
LAYER 6	X.XXXX		FR408H
	0.0012		1oz P/G
			FR408H
LAYER 7	0.0012		1oz P/G
	0.0027		FR408H
LAYER 8	0.0006		1/2oz SIG - 50 Ohms - 0.005 width
	0.0040		FR408H 100 Ohms Differential - 0.00425 width/0.00575 Space
LAYER 9	0.0006		1/2oz P/G
	0.0027		FR408H
LAYER 10	0.0020		1/2oz Sig (Std Plt) - 50 Ohms - 0.005 width
	0.0005		SOLDERMASK

DRILL CHART: TOP to LY4GND				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
a	4.0	+0.0/-4.0	PLATED	106
◆	4.01	+0.0/-4.0	PLATED	12

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
b	6.0	+0.0/-6.0	PLATED	155
c	8.0	+0.0/-8.0	PLATED	442
m	24.0	+3.0/-3.0	PLATED	17
e	25.59	+1.97/-1.97	PLATED	10
f	27.72	+2.01/-2.01	PLATED	9
g	31.65	+1.97/-1.97	PLATED	3
h	35.43	+2.01/-2.01	PLATED	5
k	40.0	+2.0/-2.0	PLATED	3
j	40.0	+2.01/-2.01	PLATED	2
p	40.0	+3.0/-3.0	PLATED	2
Ⓢ	94.49	+2.99/-2.99	NON-PLATED	4
Ⓢ	47.24x19.69	+2.0/-2.0	PLATED	4



VIEW FROM TOP SIDE

FAB NOTES:

1. ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE NOTED. ALL BOARD OUTLINE DIMENSION TOLERANCES ARE +/- .010".
2. THE PWB SHALL BE FABRICATED TO IPC-6012 CLASS 2 AND WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2. CURRENT REVISIONS.
3. BOARD MATERIAL SHALL BE ISOLA FR408HR OR EQUIVALENT, RoHS AND REACH COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. RoHS AND REACH CERTIFICATE OF CONFORMANCE SHALL BE DELIVERED WITH EACH LOT. ROHS TO BE MARKED ON THE FINISHED BOARD.
4. ALL BOARDS MUST MEET OR EXCEED UL94V-0 REQUIREMENTS. PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER.
5. MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH WITH A MINIMUM ANNULAR RING OF .002 INCH.
6. OVERALL BOARD THICKNESS TO BE .062 +/- .10% AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER. DI-ELECTRIC MATERIAL HEIGHT CAN BE UPDATED IN FAB HOUSE BASED ON MATERIAL AVAILABILITY
7. MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.
8. ANY DESCREPNCEY BETWEEN FABRICATION PRINT AND THE ACTUAL FABRICATION DATA MUST BE REVIEWED AND APPROVED BY ASSEMBLY SHOP.
9. 4 MIL & 4.01MIL BLIND VIAS TO BE FILLED WITH NON CONDUCTIVE EPOXY AND PLATED OVER COPPER.SURFACE SHOULD BE FLAT ON TOP SIDE.

PROCESS NOTES:

1. EXCEPT AS NOTED BELOW, PLATE ALL EXPOSED AREAS WITH ELECTROLESS IMMERSION GOLD, NICKEL 100 MIN MICROINCHES THK GOLD 2-6 MICROINCHES THK.
2. FABRICATOR TO REMOVE UNUSED PADS ON INTERNAL LAYERS.
3. MINIMUM TRACE/SPACE UNDER U1 IS .003/.003
4. APPLY LDI SOLDERMASK. COLOR: RED. SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H. CURRENT REV. SOLDERMASK SHALL BE COMPATIBLE WITH SAC305 OR EQUIVALENT SOLDER ALLOY AND SOLDER FLOAT BATH TEMPERATURE OF 288°C.
5. SOLDERMASK ARTWORK HAS ZERO (0) OVERSIZED PADS. FABRICATION VENDOR IS ALLOWED TO ADJUST THE COMPONENT SOLDERMASK PADS TO MEET THEIR TOOLING REQUIREMENTS WHILE MAINTAINING WEBBING BETWEEN ADJACENT PADS.
6. SOLDERABILITY SHALL BE IN ACCORDANCE WITH IPC/EIA J-STD-003A, WITH SOLDER BATH TEMPERATURE OF 250°C +/-5 C FOR DIP OR ROTARY TEST.
7. APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK. COLOR: WHITE.
8. BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.
9. VENDOR MUST SUPPLY PANELIZED PASTE LAYERS TO ASSEMBLY SHOP FOR PASTEMASK STENCIL.

CUSTOMER NAME					TEXAS INSTRUMENTS					DRAWN		
										SVT		
BOARD NAME			DLPDLCR160CPEVM			DESCRIPTION					DRILL DRAWING	
BOARD NO.			REV	DATE		PRJ#		SH		OF		
DLP094			B	03-NOV-2023		TIDL P-309772-01		17		20		